



Advances in Thermoelectric Materials and Technologies

Guest Editors:

Dr. Akhtar Naureen

Department of Engineering
Sciences, University of Agder,
4630 Kristiansand, Norway

Dr. Huey Hoon Hng

School of Materials Science and
Engineering, Nanyang
Technological University, Block
N4.1, Nanyang Avenue,
Singapore 639798, Singapore

Deadline for manuscript
submissions:

20 June 2024

Message from the Guest Editors

This Special Issue seeks original research and review articles in the latest TE and TEG research, including high-performance TE materials, efficient and reliable device design and integration, and practical applications of TE in various fields. Topics covered include but are not limited to:

- Advance thermoelectric materials—synthesis and characterization
- Novel thermoelectric devices—design, engineering, and integration
- Strategies to enhance thermoelectric efficiency and performance
- Machine learning in thermoelectric materials research
- Machine learning approaches for green energy extraction for sustainable development
- Recent thermoelectric system and applications
- Thermoelectric applications in sustainable energy area
- Concentrated solar thermal thermoelectric design





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q2 (*Engineering, Multidisciplinary*) / CiteScore - Q1 (*General Engineering*)

Contact Us

Applied Sciences Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](https://twitter.com/Applsci)